

In the Claims:



1. (currently amended) A metallic leadframe structure for use with a semiconductor chip intended for operation in a changing magnetic field, comprising:

a chip mount pad having at least one slit penetrating the whole thickness of said pad and substantially traversing the area of said pad from one edge to the opposite edge; and

said slit wide enough to interrupt electron flow in the pad plane, but not wide enough to significantly reduce thermal conduction in a direction normal to said pad plane, whereby said slit is operable to disrupt eddy currents induced in said pad by said changing magnetic field;

said device further comprising a chip wherein said chip has a n integrated circuit including a Hall device.

2. (previously presented) The leadframe according to Claim 1 wherein said slit has a width from about 0.01 to 0.5 mm.

3 (previously presented) The leadframe according to Claim 1 wherein said structure comprises a sheet-like starting configuration having a thickness in the range from about 100 to 300  $\mu\text{m}$ .

4. (previously presented) The leadframe according to Claim 3 wherein said sheet-like starting configuration is selected from a group of metals consisting of copper, copper alloy, brass, aluminum, iron-nickel alloy, and invar.

5. (previously presented) The leadframe according to Claim 1 wherein said pad has an area larger than said chip intended for mounting.

6-21. (canceled)